

## **DATASHEET**

# SMD • MID Power LED 67-21S/KK3C-HXXXXXXXXX2833Z6/2T/EU



## **Features**

- · PLCC-2 package
- Top view white LED
- High luminous intensity output
- Wide viewing angle
- Pb-free
- RoHS compliant
- ANSI Binning

## **Description**

The Everlight 67-21S package has high efficacy, high CRI, low power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for all lighting applications.

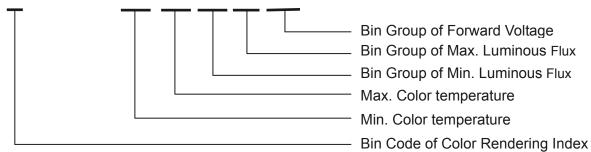
## **Applications**

- General lighting
- · Decorative and Entertainment Lighting
- Indicators
- Illumination
- · Switch lights



## **Product Number Explanation**

## 67-21S / K K 3 C - H XX XX XX XX XXX Z6 / 2T



## **Table of Color Rendering Index**

Symbol	Description
M	CRI(Min.): 60
N	CRI(Min.) : 65
L	CRI(Min.): 70
Q	CRI(Min.): 75
K	CRI(Min.): 80
Р	CRI(Min.): 85
Н	CRI(Min.): 90

Note:

Tolerance of Color Rendering Index: ±2

## **Table of Forward Current Index**

Symbol	Description
Z6	I <sub>F</sub> :60mA

#### Example:

67-21S/KK3C-H2424L9N32833Z6/2T/EU

CRI	80(Min.)		
CCT	2400K		
Flux	18~27lm		
V <sub>F</sub>	2.8~3.3V		
I <sub>F</sub>	60mA		



#### **Mass Production List**

Product	CRI Min. <sub>(1)</sub>	ССТ(К)	Φ(lm) Min. <sub>(2)</sub>	Ф(lm) Мах. <sub>(2)</sub>
67-21S/KK3C-H2020L7M42833Z6/2T/EU	80	2000K	16	24
67-21S/KK3C-H2424L9N32833Z6/2T/EU	80	2400K	18	27

#### Notes:

- 1. Tolerance of Color Rendering Index: ±2
- 2. Tolerance of Luminous flux: ±11%.





## **Device Selection Guide**

Chip Materials	Emitted Color	Resin Color
InGaN	Warm White	Water Clear

## Absolute Maximum Ratings (T<sub>Soldering</sub>=25°℃)

Parameter	Symbol	Rating	Unit
Forward Current	I <sub>F</sub>	75	mA
Peak Forward Current (Duty 1/10 @10ms)	I <sub>FP</sub>	100	mA
Power Dissipation	$P_d$	250	mW
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +100	°C
Thermal Resistance (Junction / Soldering point)	R <sub>th J-S</sub>	50	°C/W
Junction Temperature	$T_{j}$	125	°C
Soldering Temperature	T <sub>sol</sub>	T <sub>sol</sub> Reflow Soldering : 260 °C for 10 soldering : 350 °C for 3 seconds.	

#### Note:

The products are sensitive to static electricity and must be carefully taken when handling products

## Electro-Optical Characteristics (T<sub>Soldering</sub>=25℃)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Flux <sub>(1)</sub>	Ф	16		27	lm	I <sub>F</sub> =60mA
Forward Voltage <sub>(2)</sub>	$V_{F}$	2.8		3.3	V	I <sub>F</sub> =60mA
Color Rendering Index <sub>(3)</sub>	Ra	80				I <sub>F</sub> =60mA
Viewing Angle	2θ <sub>1/2</sub>		120		deg	I <sub>F</sub> =60mA
Reverse Current	lr			50	μΑ	V <sub>R</sub> =5V

#### Notes:

- 1. Tolerance of Luminous flux: ±11%.
- 2. Tolerance of Forward Voltage: ±0.1V.
- 3. Tolerance of Color Rendering Index: ±2



## **Bin Range of Luminous Flux**

Bin Code	Min.	Max.	Unit	Condition
L7	16	17		
L8	17	18	_	
L9	18	19	_ 	1 =60m A
M3	19	21	– lm	I <sub>F</sub> =60mA
M4	21	24		
N3	24	27		

Note:

Tolerance of Luminous flux: ±11%.

## **Bin Range of Forward Voltage**

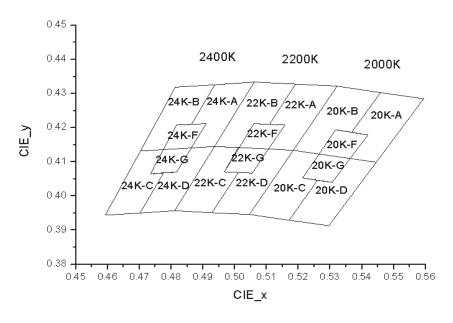
Group	Bin Code	Min.	Max.	Unit	Condition
	35	2.8	2.9		
	36	2.9	3.0		
2833	37	3.0	3.1	V	I <sub>F</sub> =60mA
	38	3.1	3.2		
	39	3.2	3.3		

Note:

Tolerance of Forward Voltage: ±0.1V.



The C.I.E. 1931 Chromaticity Diagram



**Bin Range of Chromaticity Coordinates** 

CCT	Bin Code	CIE_x	CIE_y	Bin Code	CIE_x	CIE_y		
		0.5574	0.4287		0.5398	0.4105		
		0.5423	0.4308		0.5312	0.4116		
	20K-A	0.5321	0.4193	20K-D	0.5246	0.4048		
	ZUN-A	0.5378	0.4185	20K-D	0.5199	0.4054		
		0.5312	0.4116		0.5097	0.3938		
		0.5398	0.4105		0.5221	0.3922		
	Reference Range:1850K~1990K							
	20K-B	0.5423	0.4308	- 20K-C	0.5207	0.4130		
2000K		0.5265	0.4330		0.5119	0.4142		
2000K		0.5119	0.4142		0.4973	0.3954		
		0.5207	0.4130		0.5097	0.3938		
		0.5262	0.4201		0.5199	0.4054		
		0.5321	0.4193		0.5152	0.4060		
		R	eference Range:	1990K~2130K				
		0.5378	0.4185		0.5312	0.4116		
	20K-F	0.5262	0.4201	20K C	0.5207	0.4130		
	ZUN-F	0.5207	0.4130	20K-G	0.5152	0.4060		
		0.5312	0.4116		0.5246	0.4048		
		R	eference Range:	1940K~2045K				



## **Bin Range of Chromaticity Coordinates**

ССТ	Bin Code	CIE_x	CIE_y	Bin Code	CIE_x	CIE_y		
		0.5061	0.4334		0.4936	0.4145		
		0.4937	0.4326		0.4863	0.4141		
	24K-A	0.4864	0.4210	24K-D	0.4817	0.4070		
	24N-A	0.4910	0.4212	24N-D	0.4776	0.4068		
		0.4863	0.4141		0.4702	0.3950		
		0.4936	0.4145		0.4811	0.3957		
	Reference Range:2315K~2440K							
	24K-B	0.4937	0.4326	24K-C	0.4775	0.4136		
2400K		0.4813	0.4319		0.4703	0.4132		
2400K		0.4703	0.4132		0.4593	0.3944		
		0.4775	0.4136		0.4702	0.3950		
		0.4817	0.4208		0.4776	0.4068		
		0.4864	0.4210		0.4735	0.4065		
	Reference Range:2440K~2580K							
		0.4910	0.4212		0.4863	0.4141		
	24K-F	0.4817	0.4208	24K-G	0.4775	0.4136		
	24N-F	0.4775	0.4136	24N-G	0.4735	0.4065		
		0.4863	0.4141		0.4817	0.4070		
		R	eference Range:	1910K~1995K		_		

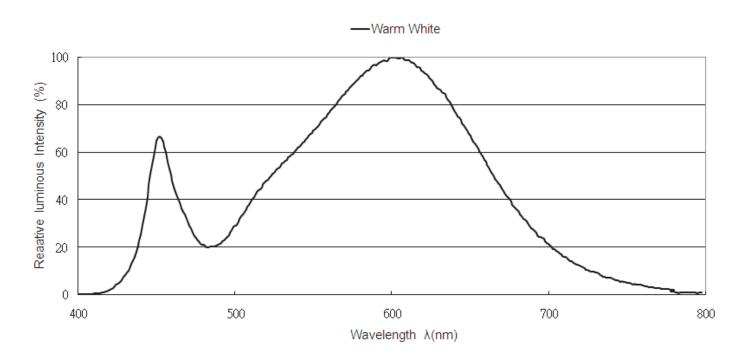
#### Notes:

## **Spectrum Distribution**

<sup>1.</sup> The value is based on driving current by 60mA.

<sup>2.</sup> Tolerance of Chromaticity Coordinates: ±0.01.





## **Typical Electro-Optical Characteristics Curves**

Fig.1 – Forward Voltage Shift vs. Junction Temperature

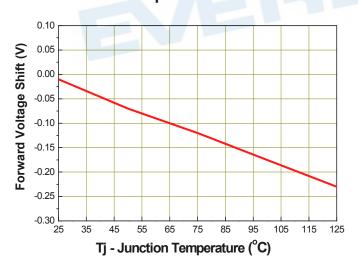
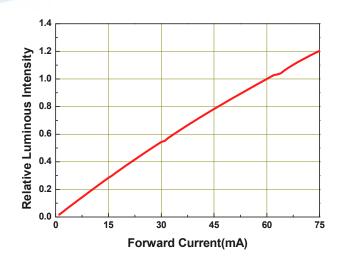


Fig.2 - Relative Luminous Intensity vs. Forward Current





## **Typical Electro-Optical Characteristics Curves**

Fig.3 - Relative Luminous Intensity vs. Junction Temperature

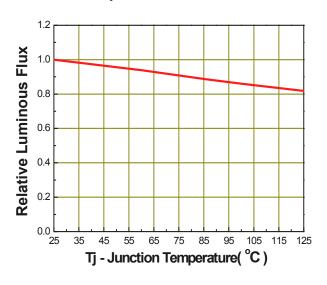


Fig.4 - Forward Current vs. Forward Voltage

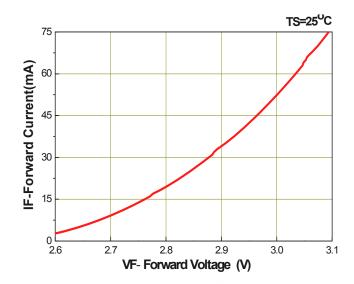


Fig.5 – Max. Driving Forward Current vs. Soldering Temperature



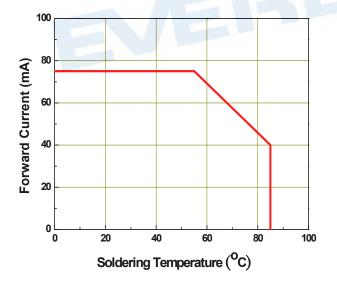
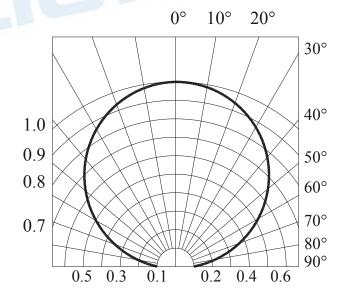
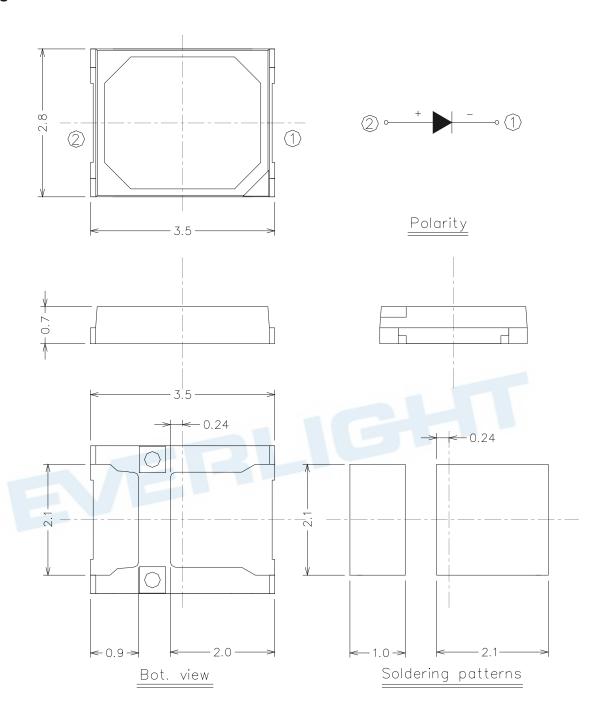


Fig.6 - Radiation Diagram





## **Package Dimension**



#### Note:

Tolerance unless mentioned is ±0.15 mm; Unit = mm



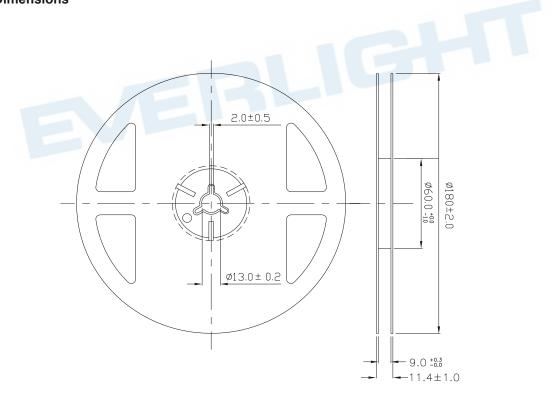
## **Moisture Resistant Packing Materials**

#### **Label Explanation**



- CPN: Customer's Product Number
- P/N: Product NumberQTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength RankREF: Forward Voltage Rank
- · LOT No: Lot Number

#### **Reel Dimensions**



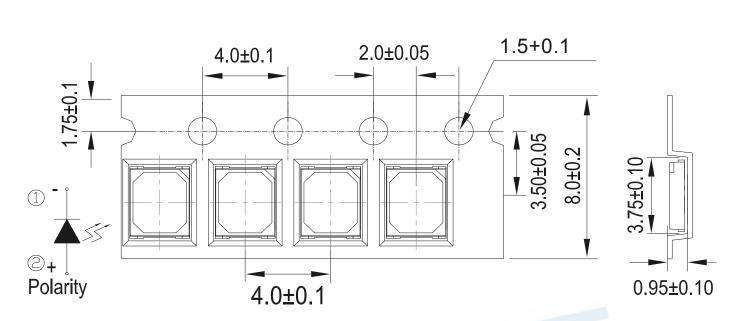
#### Note:

Tolerances unless mentioned ±0.1mm. Unit = mm



## Carrier Tape Dimensions: Loaded Quantity 4000 pcs Per Reel

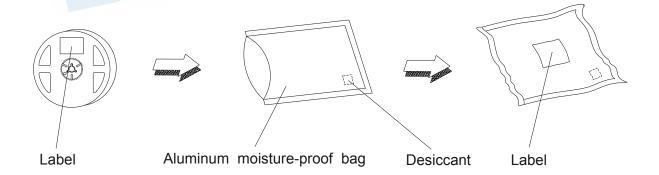
## Progressive direction



#### Note:

1.Tolerance unless mentioned is ±0.1mm; Unit = mm

## **Moisture Resistant Packing Process**





## **Reliability Test Items and Conditions**

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

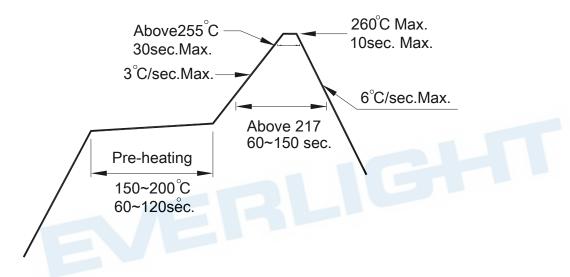
LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp.: 260°C/10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100°C 20min ∫ 10 sec L : -10°C 20min	200 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100°C 30min ∫ 5 min L : -40°C 30min	200 Cycles	22 PCS.	0/1
4	High Temperature/Humidity Reverse Bias	Ta=85°C,85%RH	1000 Hrs.	22 PCS.	0/1
5	High Temperature/Humidity Operation	Ta=85°C,85%RH, I <sub>F</sub> = 40 mA	1000 Hrs.	22 PCS.	0/1
6	Low Temperature Storage	Ta=-40°C	1000 Hrs.	22 PCS.	0/1
7	High Temperature Storage	Ta=85°C	1000 Hrs.	22 PCS.	0/1
8	Low Temperature Operation Life	Ta=-40°C, I <sub>F</sub> = 75 mA	1000 Hrs.	22 PCS.	0/1
9	High Temperature Operation/ Life#1	Ta=25°C, I <sub>F</sub> = 75 mA	1000 Hrs.	22 PCS.	0/1
10	High Temperature Operation/ Life#2	Ta=55°C, I <sub>F</sub> =75 mA	1000 Hrs.	22 PCS.	0/1
11	High Temperature Operation/ Life#3	Ta=85°C, I <sub>F</sub> = 40 mA	1000 Hrs.	22 PCS.	0/1



#### **Precautions for Use**

- 1. Over-current-proof
  - Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).
- 2. Storage
  - 2.1 Do not open moisture proof bag before the products are ready to use.
  - 2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.
  - 2.3 After opening the package: The LED's floor life is 168 Hrs under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
  - 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
    - Baking treatment: 60±5°C for 24 hours.
- 3. Soldering Condition
  - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

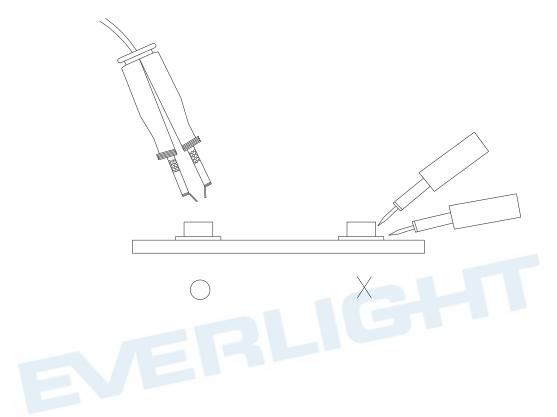


#### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

#### Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



#### **DISCLAIMER**

- EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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